ATDK Product Center					myTDK Ab	bout TDK	English 🗸	Q	TDK Worldwide
News	Products	Catalog	Application Guides	Technical Support	Tech Library	Environment	Contact		
- in $ angle$ Pri $ angle$ Ca	a 📏 Multilayer Ce	ramic Chip Capacitors	Detailed Information						

Multilayer Ceramic Chip Capacitors

	Product Top Page	Search by Part No.	Search by Characteristics	Cross Reference	Catalog	Tech Notes	more			
(C2012X7R2A222K085AA							?		

TDK item description ?	C2012X7R2A222KT****		
Applications	Commercial Grade Please refer to Part No. <u>CGA4F2X7R2A222K085AA</u> for Automotive use.		
Feature	Mid Wiltage (100 to 630V)		
Series	C2012 [EIA 0805]		
Status	Production (Not Recommended for New Design)		



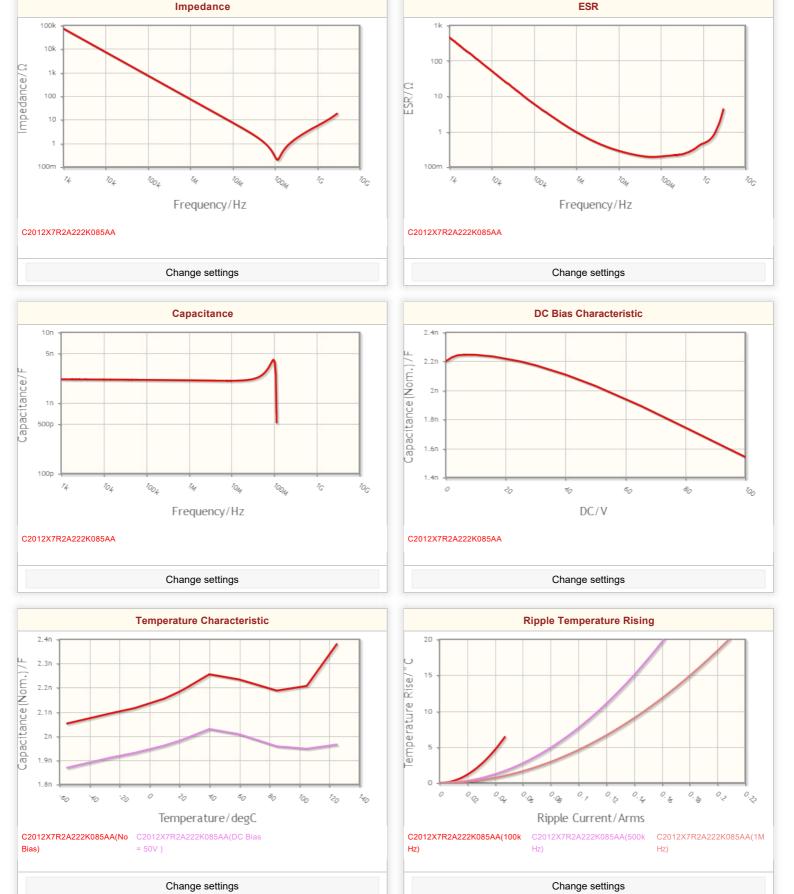
Images are for reference only and show exemplary products.

Size	
Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	0.85mm ±0.15mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering) 0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering) 0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics	
Capacitance	2.2nF ±10%
Rated Voltage	100VDC
Temperature Characteristic ?	X7R(±15%)
Dissipation Factor (Max.)	3%
Insulation Resistance (Min.)	10000ΜΩ

Other	
Soldering Method	Wave (Flow) Reflow
AEC-Q200	No
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	4000pcs

Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)





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Power Supplies	
Magnets	
Flash Storages	
Wireless Power Transfer	
FA Systems	
Transparent Conductive Film	
Micro Modules (Substrates with Built-in ICs, Products Utilizing with SESUB)	
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